DNP=DO NOT POPULATE

PMP11774 REV C Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1	1	150uF	EEU-FR1E151B	Panasonic	CAP, AL, 150 µF, 25 V, +/- 20%, ohm, TH	D6.3xL11.2mm
C2, C8	2	10uF	GRM32ER71H106KA12L	MuRata	CAP, CERM, 10uF, 50V, +/-10%, X7R, 1210	1210
C3	1	DNP	QMK212B7102KD-T	Taiyo Yuden	CAP, CERM, 1000 pF, 250 V, +/- 10%, X7R, 0805	0805
C4	1	15uF	EEUED2G150	Panasonic	CAP, AL, 15 µF, 400 V, +/- 20%, 1.909859 ohm, TH	12.5x20
C5	1	0.1uF	R46KF310050P0K	Kemet	CAP, Film, 0.1 µF, 560 V, +/- 10%, TH	13x12x6mm
C6	1	330uF	10ZLH330MEFC6.3X11	Rubycon	CAP, AL, 330 µF, 10 V, +/- 20%, 0.094 ohm, TH	Radial Leaded, 2-Leads, Dia 6.3mm, Height 11mm, Pin Spacing 2.5mm
C7	1	100uF	EEU-FM1E101	Panasonic	CAP, AL, 100 µF, 25 V, +/- 20%, 0.13 ohm, TH	6.3x11.2mm
C9	1	0.1uF	06035C104KAT2A	AVX	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603
C10	1	22uF	GRM32ER61E226KE15L	MuRata	CAP, CERM, 22 µF, 25 V, +/- 10%, X5R, 1210	1210
C11, C12	2	DNP	06035A100JAT2A	AVX	CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0603, CAP, CERM, 10pF, 50V, +/-5%, C0G/NP0, 0603	0603
D1	1	STPS1150A	STPS1150A	ST Microelectronics	Diode, Schottky, 150V, 1A, SMA	SMA
D2	1	DNP	DFLR1600-7	Diodes Inc.	Diode, Standard Recovery Rectifier, 600 V, 1 A, PowerDI123	PowerDI123
D3	1	60V	B160-13-F	Diodes Inc.	Diode, Schottky, 60 V, 1 A, SMA	SMA
D4	1	150V	BAV20WS-TP	Micro Commercial Component	Diode, P-N, 150 V, 0.2 A, SOD-323	SOD-323
D5	1	20V	BZX84C20LT1G	ON Semiconductor	Diode, Zener, 20 V, 225 mW, SOT-23	SOT-23
D6	1	600V	DF06M	Diodes Inc.	Diode, Switching-Bridge, 600 V, 1 A, TH	Diodge Bridge
D7	1	6.8V	BZX84C6V8LT1G	ON Semiconductor	Diode, Zener, 6.8 V, 225 mW, SOT-23	SOT-23
GND.1, Neutral	2	Black	5001	Keystone	Test Point, TH, Miniature, Black	Keystone5001
J1	1		1757255	TE Connectivity	Terminal Block, 5.08mm, 3x1, TH	17.24x8.6x12mm
J2	1		770W-X2/10	Qualtek Electronics Corporatio	AC Receptacle, 2.5A, R/A, TH	AC, Reception 14.5x15x22 mm
J3	1		923345-05-C	3M	Jumper Wire, 500mil spacing, Green, pkg of 200	500 mil Jumper Wire
L1	1	1mH	744743102	Wurth Elektronik	Inductor, Wirewound, Ferrite, 1 mH, 0.42 A, 2.2 ohm, TH	2-Pin Radial Leaded, Dia 8 mm, Height 12.5 mm, Pin Spacing 5 mm
L2	1	short	744743102	Wurth Elektronik	Inductor, Wirewound, Ferrite, 1 mH, 0.42 A, 2.2 ohm, TH	2-Pin Radial Leaded, Dia 8 mm, Height 12.5 mm, Pin Spacing 5 mm
Line, TP1, TP2	3	Red	5000	Keystone	Test Point, TH, Miniature, Red	Keystone5000
R1	1	DNP	RC1206FR-07120KL	Yageo America	RES, 120 k, 1%, 0.25 W, 1206	1206
R2	1	10 ohm	B57236S0100M000	EPCOS Inc	Thermistor NTC, 10 ohm, 20%, Disc_11.5mmx6mm	Disc_11.5mmx6mm
R3, R8	2	10k	CRCW080510K0JNEA	Vishay-Dale	RES, 10 k, 5%, 0.125 W, 0805	0805
R4	1	10.0k	RC1206FR-0710KL	Yageo America	RES, 10.0 k, 1%, 0.25 W, 1206	1206
R5	1	DNP	CRCW08050000Z0EA	Vishay-Dale	RES, 0, 5%, 0.125 W, 0805	0805
R6	1	0	CRCW08050000Z0EA	Vishay-Dale	RES, 0, 5%, 0.125 W, 0805	0805
R7	1	DNP	CRCW120610R0JNEA	Vishay-Dale	RES, 10, 5%, 0.25 W, 1206	1206
R9	1	DNP	RC1206FR-0710KL	Yageo America	RES, 10.0 k, 1%, 0.25 W, 1206	1206
R10	1	10	CRCW060310R0JNEAHP	Vishay-Dale	RES, 10, 5%, 0.25 W, 0603	0603
R11	1	DNP	CRCW0603110KFKEA	Vishay-Dale	RES, 110 k, 1%, 0.1 W, 0603	0603
R12	1	23.7k	CRCW060323K7FKEA	Vishay-Dale	RES, 23.7 k, 1%, 0.1 W, 0603	0603

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
R13	1	1.38k	RT0603BRD071K38L	Yageo America	RES, 1.38 k, 0.1%, 0.1 W, 0603	0603
R14	1	DNP	CRCW060391K0JNEA	Vishay-Dale	RES, 91 k, 5%, 0.1 W, 0603	0603
R15	1	61.9k	RC0603FR-0761K9L	Yageo America	RES, 61.9 k, 1%, 0.1 W, 0603	0603
R16, R116	2	Jumper Wire		Stackpole Electronics Inc	RES, 47, 5%, 0.25 W, Axial	Axial
R17	1	0	CRCW12060000Z0EA	Vishay-Dale	RES, 0, 5%, 0.25 W, 1206	1206
T1	1	750315942_Rev01	750315942_Rev01	Texas Instruments	Transformer, TH	20.3x17.96
U1	1		UCC28911DR	Texas Instruments	High Voltage Flyback Switcher with Primary-side Regulation and Constant-Current Control, D0007A	D0007A

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